

LM10504

Flexible Integrated Power Management Unit



Product Bulletin

High Efficiency Solution Optimized for Solid State Drives

Overview

The LM10504 from Texas Instruments is a fully integrated power management unit (PMU) capable of powering all supply rails in Solid State Drives (SSD). This ultra-compact, reliable/flexible, and highly efficient power solution replaces up to four (4) discrete components typically used in these drives. It functions cooperatively with a controller IC to optimize the supply voltage for low power conditions and features additional proprietary power saving modes to obtain maximum system efficiency.

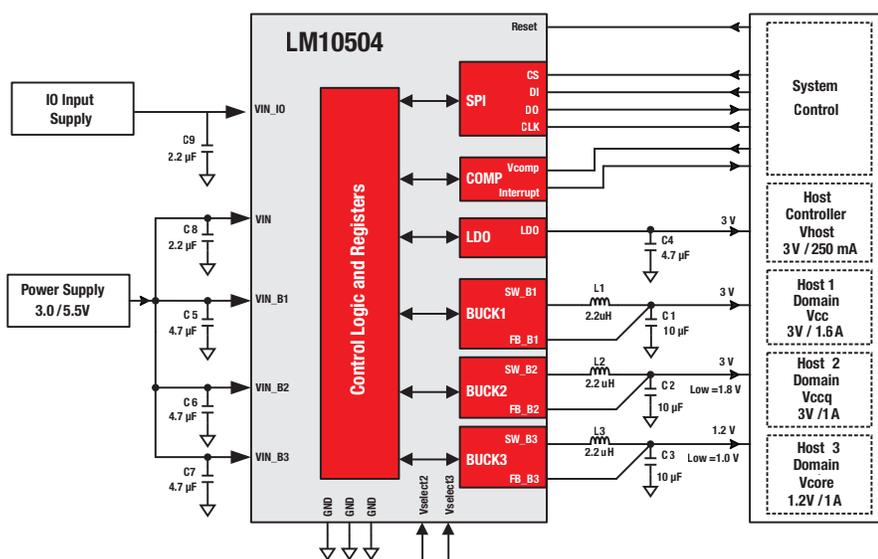
This design scheme delivers longer battery life for portable devices with solid state drives. The chip also uses a 4-wire SPI interface to communicate with processors to achieve output voltage programmability. Unlike discrete solutions available today, the highly integrated, all-in-one PMU solution from TI delivers a higher performance to cost ratio and is specifically designed and optimized with features geared for SSD and flash drive applications.

Product Highlights

- Three highly efficient SPI-programmable buck regulators plus an LDO
- Power down data protection
- Deep Sleep mode saves power during idle times
- Automatic internal soft-start on each supply limits startup inrush current
- Phase-shifted buck operation reduces input current ripple and capacitor size

Key Specifications

- $\pm 3\%$ feedback voltage accuracy
- Up to 95% efficient buck regulators
- 2 MHz switching frequency for smaller inductor size
- 2.8 x 2.8 mm with 0.4 mm pitch microSMD package



LM10504 typical application diagram

Features and Benefits

Better performance to cost ratio compared to discrete solutions

- Integrated all-in-one power solution saves valuable board space
- 2 MHz switching frequency for smaller inductor size
- High bandwidth provides fast turn-on without overshoot
- No loop compensation needed
- PFM mode for low load high efficiency operation

Reliability and flexibility at a low cost

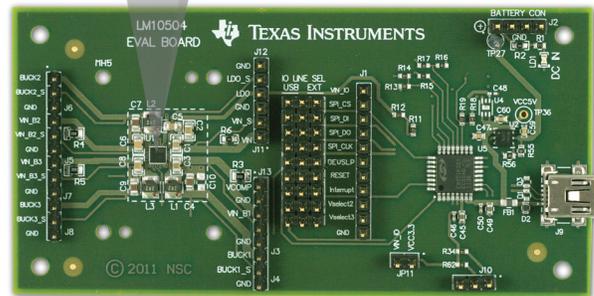
- Built-in over-current limit and thermal protection improves safety
- All three supply voltages offer user-programmable options for maximum flexibility
- Customizable startup sequencing for greater flexibility
- Bypass mode on Buck1 and Buck2 for power down data protection to enhance data integrity
- Easy-to-interface GUI for accelerated design
- Integrated solution leads to higher overall reliability of SSD

Extremely energy-efficient design

- Operates cooperatively with ASIC to optimize the supply voltage for low power conditions
 - Dynamic Voltage Scaling (DVS)
- Power saving modes via SPI interface
 - Sleep mode (DEVSLP) and DVS

Regulator Table

Regulator	Programmable V_{OUT}	Maximum Output Current	Description
Buck1	1.1 – 3.6V, 50 mV steps	1.6A	Flash power
Buck2	1.1 – 3.6V, 50 mV steps	1A	Interface
Buck3	0.7 – 1.335V, 5 mV steps	1A	Core
LDO	1.2 – 3.1V	250 mA	Reference for host



LM10504 evaluation board

LM10504 SSD solution board demonstrates the reduced size possible with the integrated PMU, actual size 13 mm x 10 mm



Visit ti.com/LM10504 for more product information.

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